

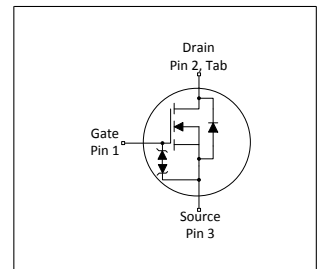
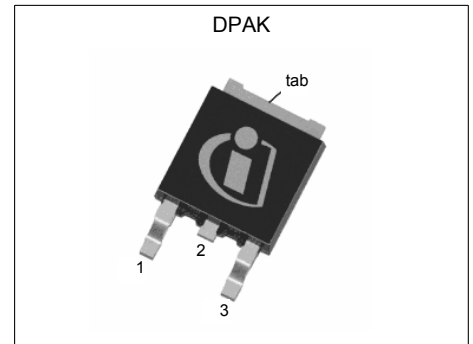
MOSFET

700V CoolMOS™ P7 Power Transistor

CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies.

The latest CoolMOS™ P7 is an optimized platform tailored to target cost sensitive applications in consumer markets such as charger, adapter, lighting, TV, etc.

The new series provides all the benefits of a fast switching Superjunction MOSFET, combined with an excellent price/performance ratio and state of the art ease-of-use level. The technology meets highest efficiency standards and supports high power density, enabling customers going towards very slim designs.



Features

- Extremely low losses due to very low FOM $R_{DS(on)} * Q_g$ and $R_{DS(on)} * E_{oss}$
- Excellent thermal behavior
- Integrated ESD protection diode
- Low switching losses (E_{oss})
- Product validation acc. JEDEC Standard

Benefits

- Cost competitive technology
- Lower temperature
- High ESD ruggedness
- Enables efficiency gains at higher switching frequencies
- Enables high power density designs and small form factors

Potential applications

Recommended for Flyback topologies for example used in Chargers, Adapters, Lighting Applications, etc.

Please note: For MOSFET paralleling the use of ferrite beads on the gate or separate totem poles is generally recommended.



Table 1 Key Performance Parameters

| Parameter | Value | Unit |
|----------------------------|-------|----------|
| $V_{DS} @ T_j=25^{\circ}C$ | 700 | V |
| $R_{DS(on),max}$ | 0.36 | Ω |
| $Q_{g,typ}$ | 16.4 | nC |
| $I_{D,pulse}$ | 34 | A |
| $E_{oss} @ 400V$ | 1.8 | μJ |
| $V_{(GS)th,typ}$ | 3 | V |
| ESD class (HBM) | 2 | |

| Type / Ordering Code | Package | Marking | Related Links |
|----------------------|-------------|----------|----------------|
| IPD70R360P7S | PG-TO 252-3 | 70S360P7 | see Appendix A |

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1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|--|----------------|------------|------|-------------|------------------|--|
| | | Min. | Typ. | Max. | | |
| Continuous drain current ¹⁾ | I_D | - | - | 12.5 7.5 | A | $T_C = 20^\circ\text{C}$ $T_C = 100^\circ\text{C}$ |
| Pulsed drain current ²⁾ | $I_{D,pulse}$ | - | - | 34.0 | A | $T_C=25^\circ\text{C}$ |
| Application (Flyback) relevant avalanche current, single pulse ³⁾ | I_{AS} | - | - | 4.5 | A | measured with standard leakage inductance of transformer of 10 μH |
| MOSFET dv/dt ruggedness | dv/dt | - | - | 100 | V/ns | $V_{DS} = 0 \dots 400\text{V}$ |
| Gate source voltage | V_{GS} | -16 -30 | - | 16 30 | V | static; AC ($f > 1\text{ Hz}$) |
| Power dissipation | P_{tot} | - | - | 59.5 | W | $T_C=25^\circ\text{C}$ |
| Operating and storage temperature | T_j, T_{stg} | -40 | - | 150 | $^\circ\text{C}$ | - |
| Continuous diode forward current | I_S | - | - | 8.5 | A | $T_C=25^\circ\text{C}$ |
| Diode pulse current ²⁾ | $I_{S,pulse}$ | - | - | 34.0 | A | $T_C = 25^\circ\text{C}$ |
| Reverse diode dv/dt ⁴⁾ | dv/dt | - | - | 1 | V/ns | $V_{DS} = 0 \dots 400\text{V}$, $I_{SD} \leq I_S$, $T_j=25^\circ\text{C}$ |
| Maximum diode commutation speed ⁴⁾ | di/dt | - | - | 50 | A/ μs | $V_{DS} = 0 \dots 400\text{V}$, $I_{SD} \leq I_S$, $T_j=25^\circ\text{C}$ |
| Insulation withstand voltage | V_{ISO} | - | - | n.a. | V | V_{rms} , $T_C=25^\circ\text{C}$, $t=1\text{ min}$ |

2 Thermal characteristics

Table 3 Thermal characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|---|-------------|--------|------|------|--------------------|--|
| | | Min. | Typ. | Max. | | |
| Thermal resistance, junction | R_{thJC} | - | - | 2.1 | $^\circ\text{C/W}$ | - |
| Thermal resistance, junction - ambient | R_{thJA} | - | - | 62 | $^\circ\text{C/W}$ | Device on PCB, minimal footprint |
| Thermal resistance, junction - ambient for SMD version | R_{thJA} | - | 35 | 45 | $^\circ\text{C/W}$ | Device on 40mm*40mm*1.5 epoxy PCB FR4 with 6cm ² (one layer 70 μm thickness) copper area for drain connection and cooling. PCB is vertical without air stream cooling. |
| Soldering temperature, wave- & reflow soldering allowed | T_{solid} | - | - | 260 | $^\circ\text{C}$ | reflow MSL3 |

¹⁾ Limited by $T_{j,max}$. $T_j = 20^\circ\text{C}$. Maximum duty cycle $D=0.5$

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Proven during verification test. For explanation please read AN - CoolMOS™ 700V P7.

⁴⁾ $V_{DClink}=400\text{V}$; $V_{DS,peak} < V_{(BR)DSS}$; identical low side and high side switch with identical R_G

3 Electrical characteristics

Table 4 Static characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|---|---------------|--------|--------------|-----------|----------|---|
| | | Min. | Typ. | Max. | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | 700 | - | - | V | $V_{GS}=0V, I_D=1mA$ |
| Gate threshold voltage | $V_{(GS)th}$ | 2.50 | 3 | 3.50 | V | $V_{DS}=V_{GS}, I_D=0.15mA$ |
| Zero gate voltage drain current | I_{DSS} | - | - | 1 | μA | $V_{DS}=700V, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=700V, V_{GS}=0V, T_j=150^\circ C$ |
| Gate-source leakage current incl. Zener diode | I_{GSS} | - | - | 1 | μA | $V_{GS}=20V, V_{DS}=0V$ |
| Drain-source on-state resistance | $R_{DS(on)}$ | - | 0.30 0.67 | 0.36 - | Ω | $V_{GS}=10V, I_D=3.0A, T_j=25^\circ C$ $V_{GS}=10V, I_D=3.0A, T_j=150^\circ C$ |
| Gate resistance | R_G | - | 30 | - | Ω | $f=1\text{ MHz, open drain}$ |

Table 5 Dynamic characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|--|--------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Input capacitance | C_{iss} | - | 517 | - | pF | $V_{GS}=0V, V_{DS}=400V, f=250kHz$ |
| Output capacitance | C_{oss} | - | 11 | - | pF | $V_{GS}=0V, V_{DS}=400V, f=250kHz$ |
| Effective output capacitance, energy related ¹⁾ | $C_{o(er)}$ | - | 27 | - | pF | $V_{GS}=0V, V_{DS}=0...400V$ |
| Effective output capacitance, time related ²⁾ | $C_{o(tr)}$ | - | 329 | - | pF | $I_D=constant, V_{GS}=0V, V_{DS}=0...400V$ |
| Turn-on delay time | $t_{d(on)}$ | - | 19 | - | ns | $V_{DD}=400V, V_{GS}=13V, I_D=2.3A,$ $R_G=5.3\Omega$ |
| Rise time | t_r | - | 8 | - | ns | $V_{DD}=400V, V_{GS}=13V, I_D=2.3A,$ $R_G=5.3\Omega$ |
| Turn-off delay time | $t_{d(off)}$ | - | 100 | - | ns | $V_{DD}=400V, V_{GS}=13V, I_D=2.3A,$ $R_G=5.3\Omega$ |
| Fall time | t_f | - | 18 | - | ns | $V_{DD}=400V, V_{GS}=13V, I_D=2.3A,$ $R_G=5.3\Omega$ |

Table 6 Gate charge characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|-----------------------|---------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Gate to source charge | Q_{gs} | - | 2.3 | - | nC | $V_{DD}=400V, I_D=2.3A, V_{GS}=0\text{ to }10V$ |
| Gate to drain charge | Q_{gd} | - | 6.0 | - | nC | $V_{DD}=400V, I_D=2.3A, V_{GS}=0\text{ to }10V$ |
| Gate charge total | Q_g | - | 16.4 | - | nC | $V_{DD}=400V, I_D=2.3A, V_{GS}=0\text{ to }10V$ |
| Gate plateau voltage | $V_{plateau}$ | - | 4.4 | - | V | $V_{DD}=400V, I_D=2.3A, V_{GS}=0\text{ to }10V$ |

¹⁾ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 400V

²⁾ $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 400V

Table 7 Reverse diode characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|-------------------------------|-----------|--------|------|------|---------|---|
| | | Min. | Typ. | Max. | | |
| Diode forward voltage | V_{SD} | - | 0.9 | - | V | $V_{GS}=0V, I_F=3.8A, T_j=25^\circ C$ |
| Reverse recovery time | t_{rr} | - | 210 | - | ns | $V_R=400V, I_F=2.3A, di_F/dt=50A/\mu s$ |
| Reverse recovery charge | Q_{rr} | - | 1.0 | - | μC | $V_R=400V, I_F=2.3A, di_F/dt=50A/\mu s$ |
| Peak reverse recovery current | I_{rrm} | - | 10 | - | A | $V_R=400V, I_F=2.3A, di_F/dt=50A/\mu s$ |

4 Electrical characteristics diagrams

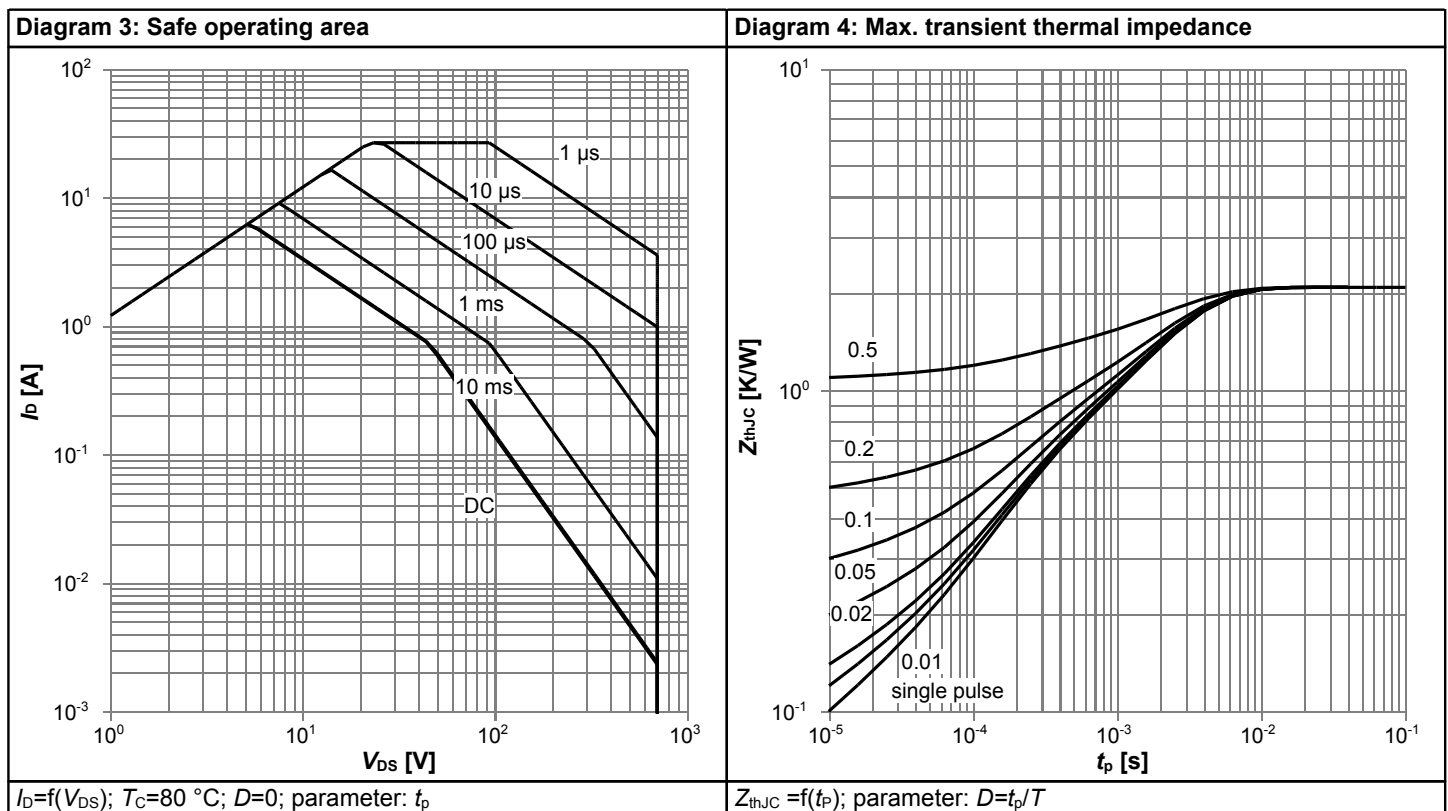
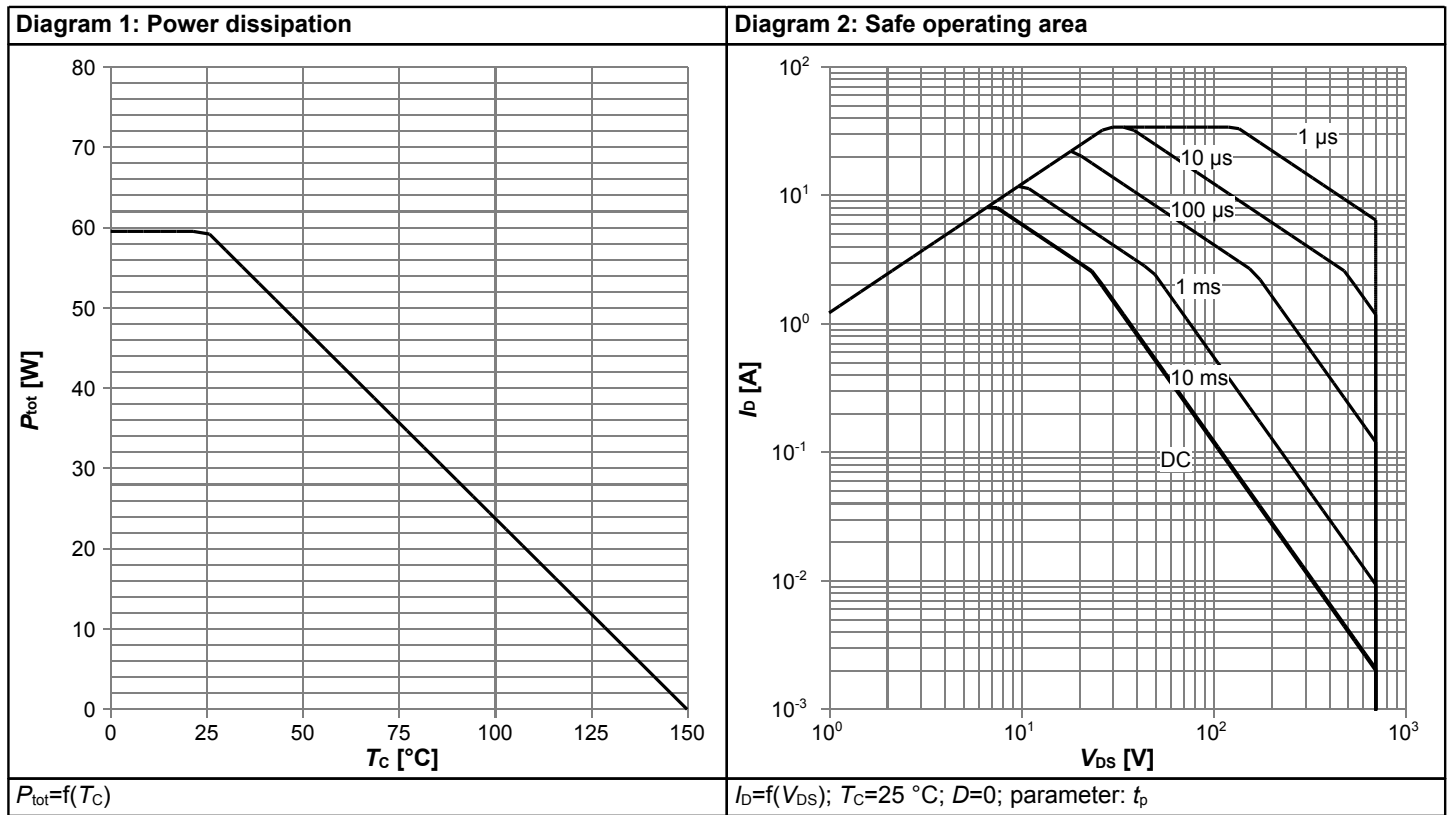
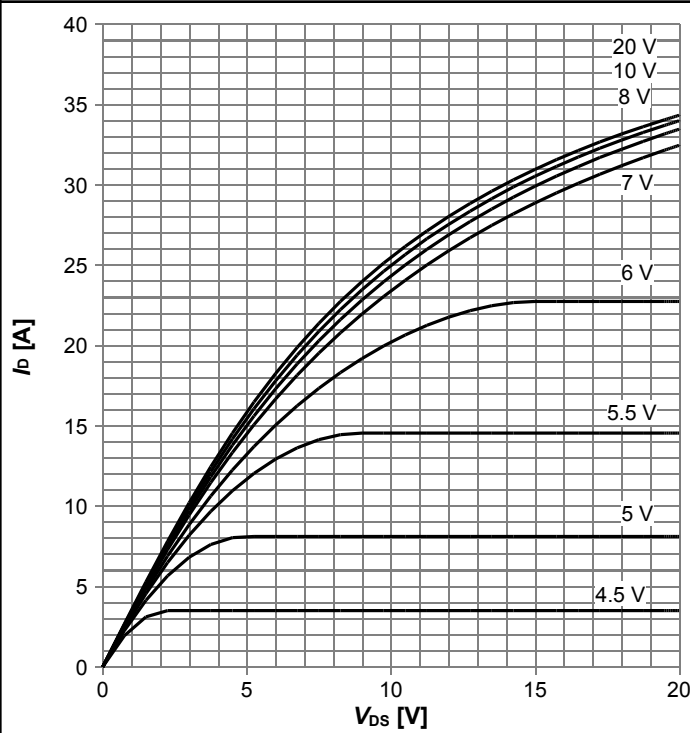
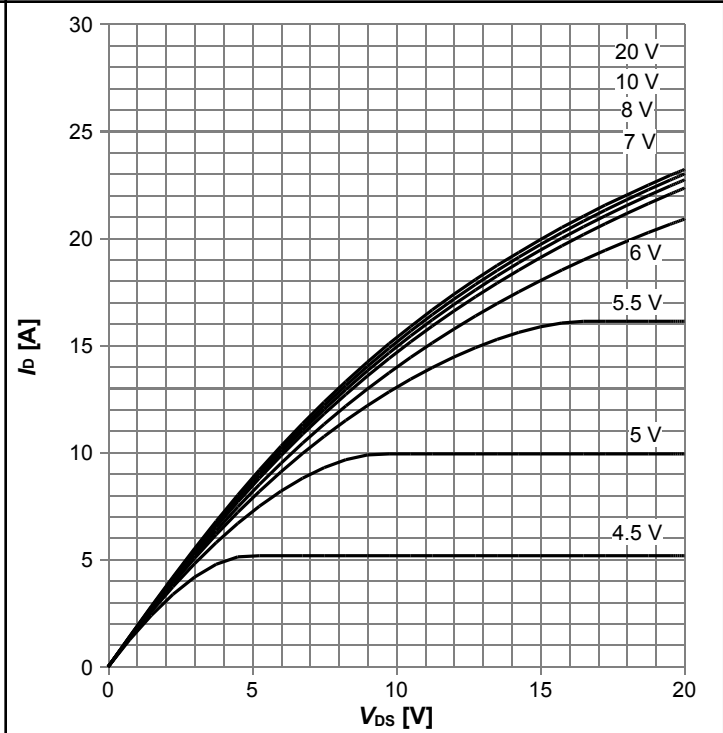


Diagram 5: Typ. output characteristics



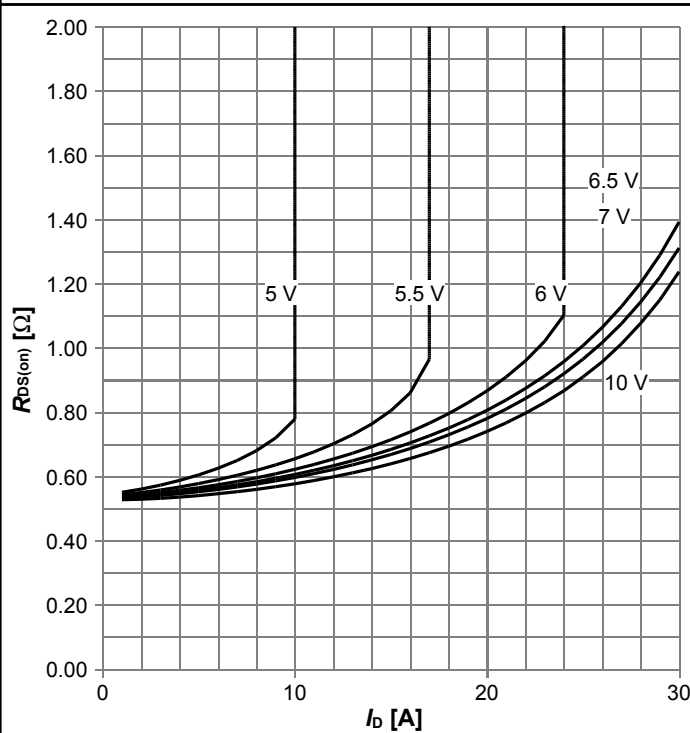
$I_D=f(V_{DS})$; $T_j=25\text{ °C}$; parameter: V_{GS}

Diagram 6: Typ. output characteristics



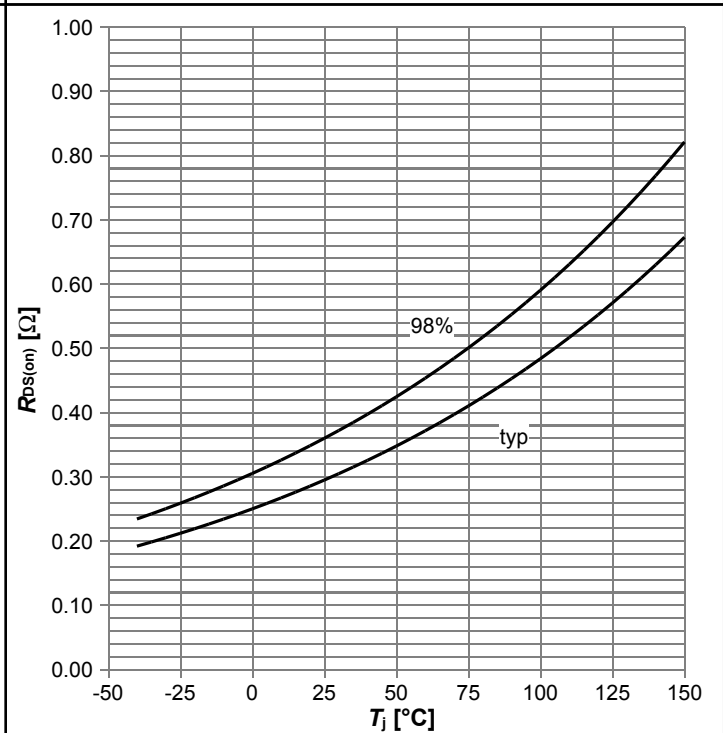
$I_D=f(V_{DS})$; $T_j=125\text{ °C}$; parameter: V_{GS}

Diagram 7: Typ. drain-source on-state resistance



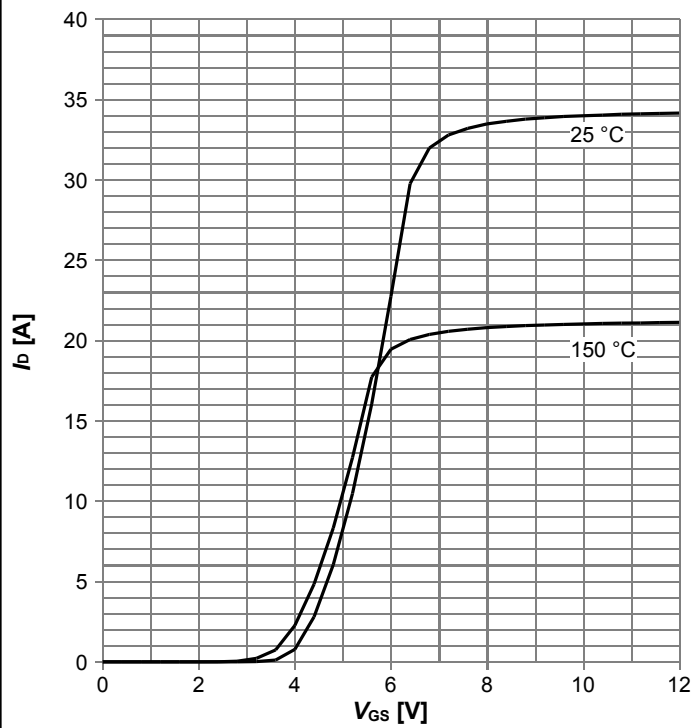
$R_{DS(on)}=f(I_D)$; $T_j=125\text{ °C}$; parameter: V_{GS}

Diagram 8: Drain-source on-state resistance



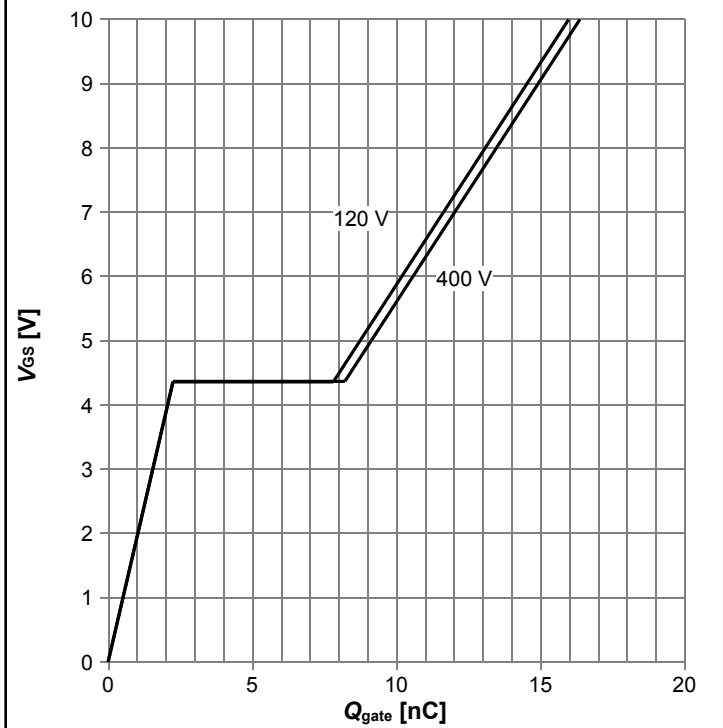
$R_{DS(on)}=f(T_j)$; $I_D=3.0\text{ A}$; $V_{GS}=10\text{ V}$

Diagram 9: Typ. transfer characteristics



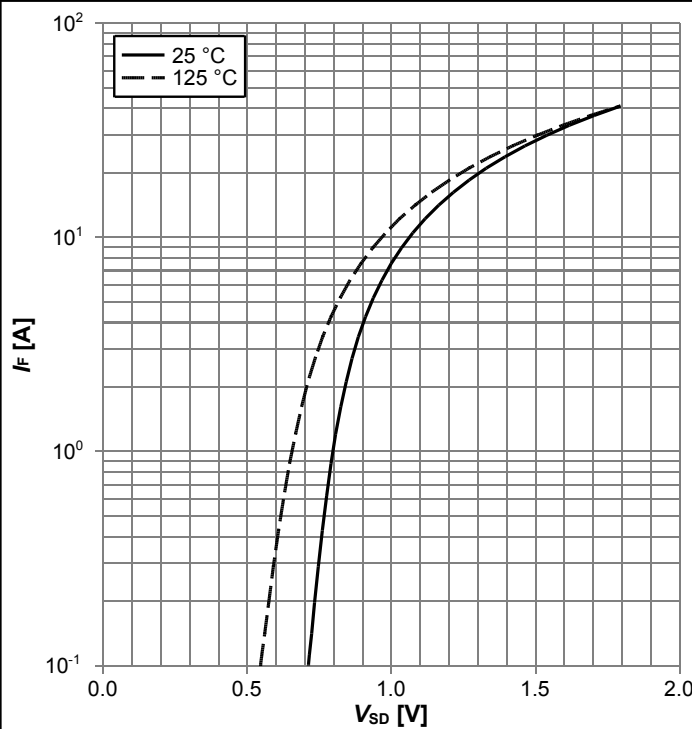
$I_D=f(V_{GS}); V_{DS}=20V; \text{parameter: } T_j$

Diagram 10: Typ. gate charge



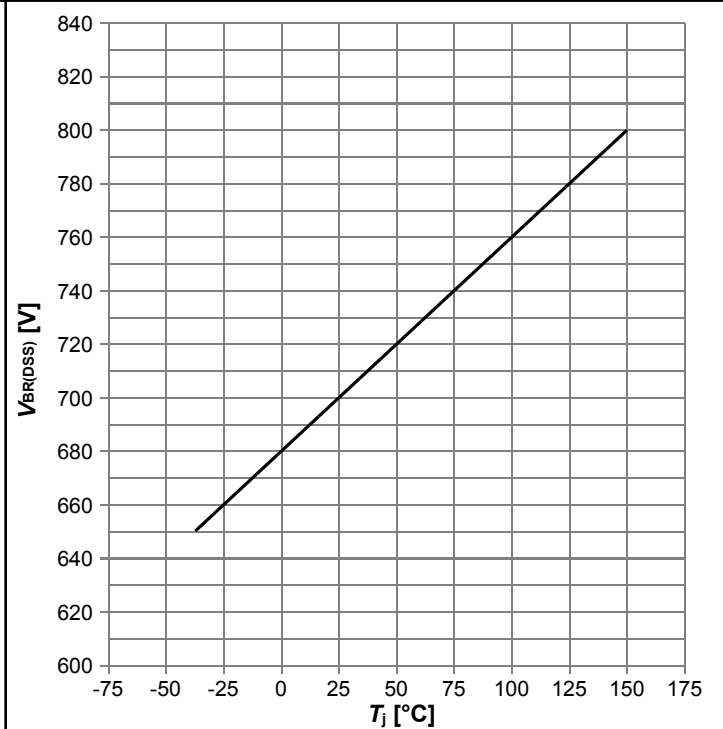
$V_{GS}=f(Q_{gate}); I_D=2.3 \text{ A pulsed}; \text{parameter: } V_{DD}$

Diagram 11: Forward characteristics of reverse diode



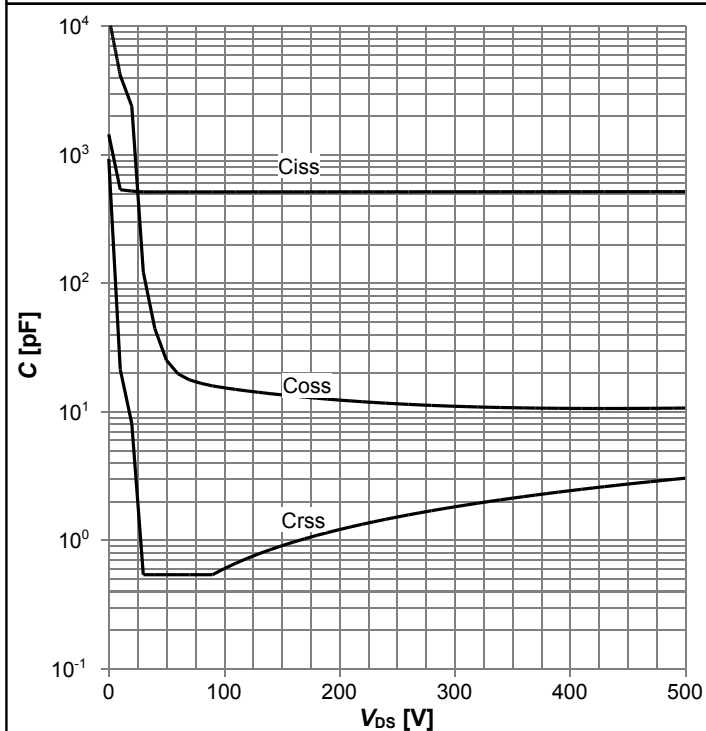
$I_F=f(V_{SD}); \text{parameter: } T_j$

Diagram 13: Drain-source breakdown voltage



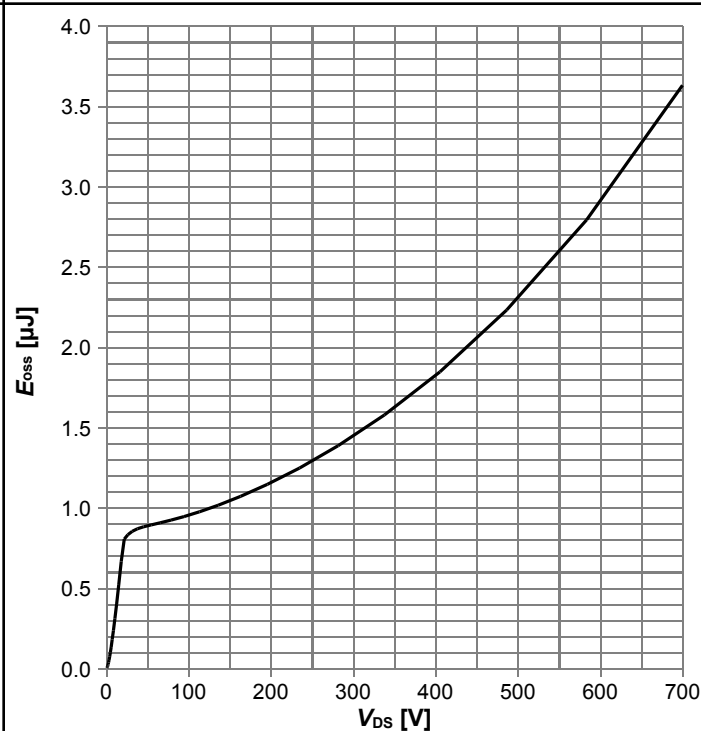
$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$

Diagram 14: Typ. capacitances



$C=f(V_{DS}); V_{GS}=0\text{ V}; f=250\text{ kHz}$

Diagram 15: Typ. Coss stored energy



$E_{oss}=f(V_{DS})$

5 Test Circuits

Table 8 Diode characteristics

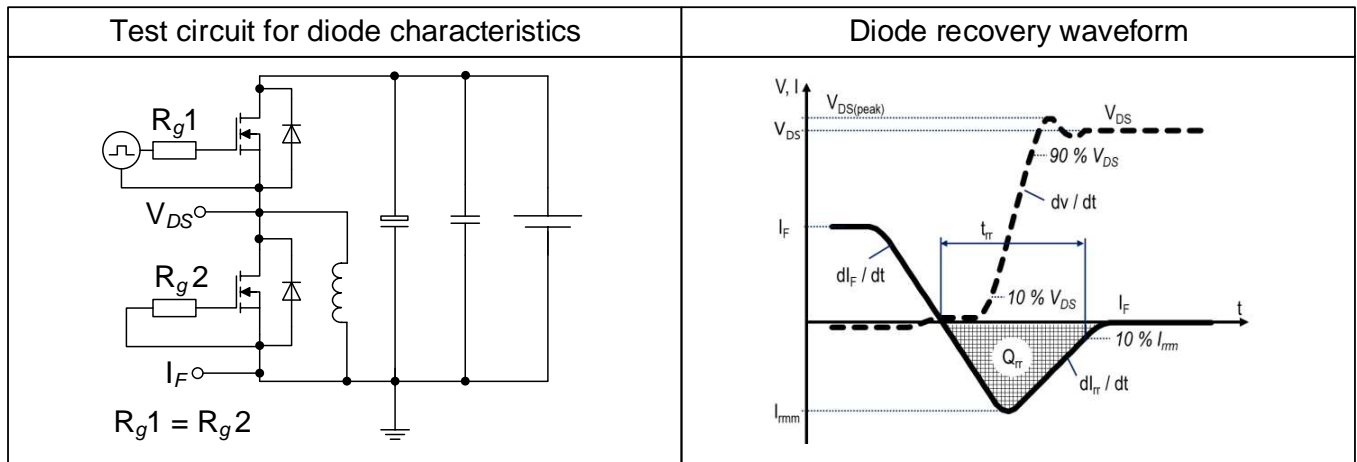


Table 9 Switching times

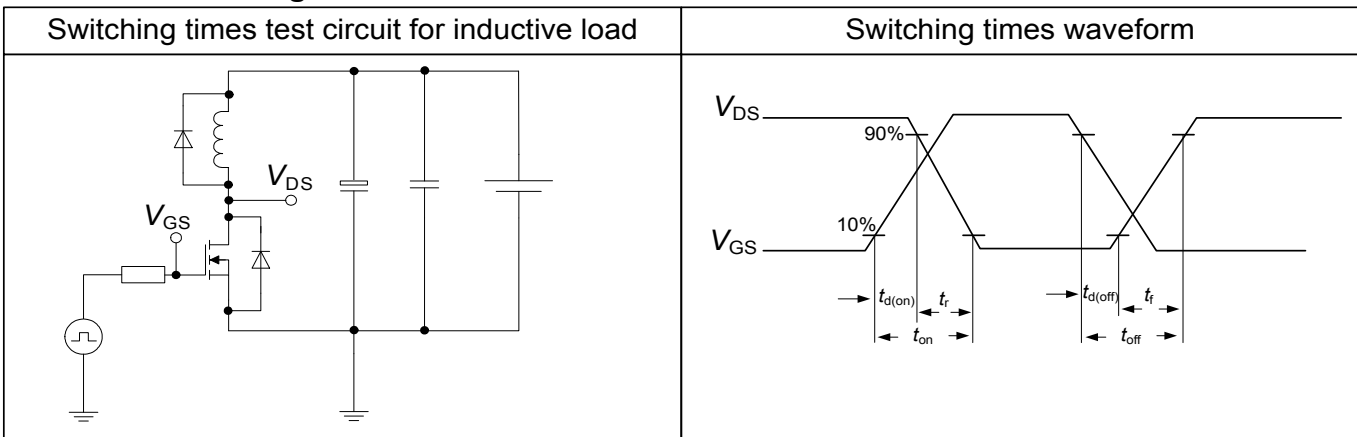
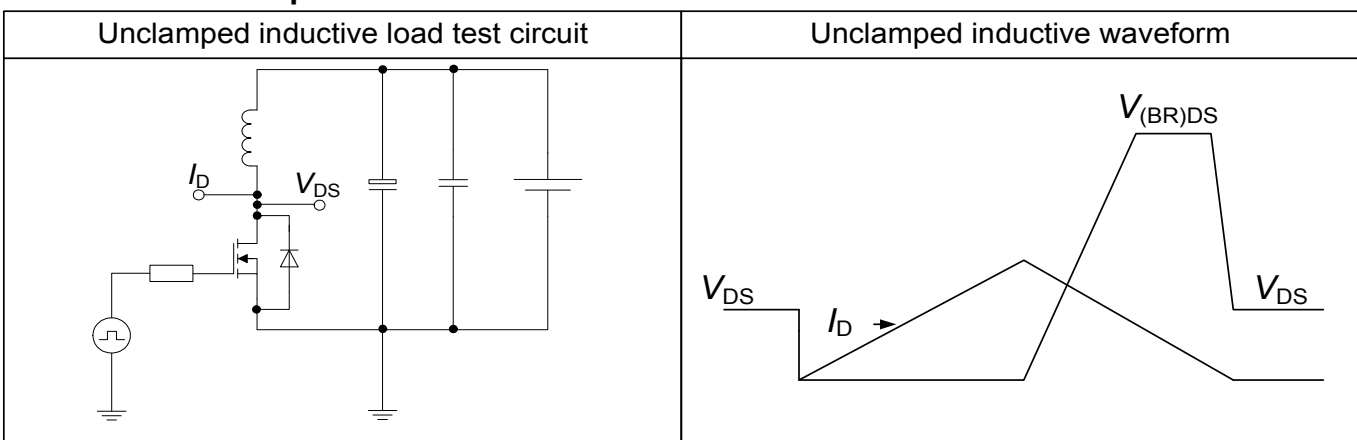


Table 10 Unclamped inductive load



6 Package Outlines

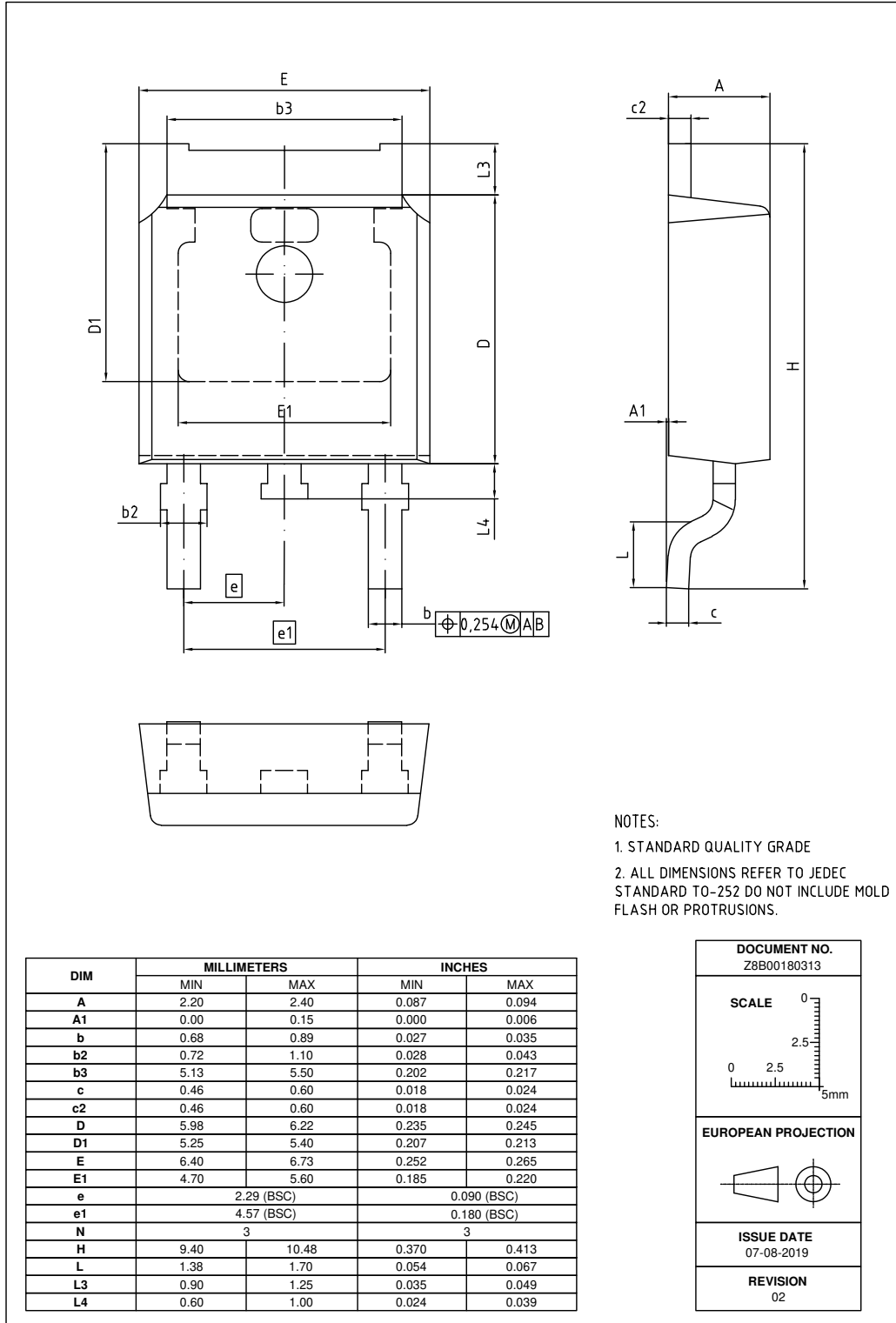


Figure 1 Outline PG-TO 252-3, dimensions in mm/inches

7 Appendix A

Table 11 Related Links

- IFX CoolMOS™ P7 Webpage: www.infineon.com
- IFX Design tools: www.infineon.com

Revision History

IPD70R360P7S

Revision: 2019-08-09, Rev. 2.2

Previous Revision

| Revision | Date | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.0 | 2016-10-11 | Release of final version |
| 2.1 | 2018-02-12 | Corrected front page text |
| 2.2 | 2019-08-09 | Updated package outline |

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